

Fig.1

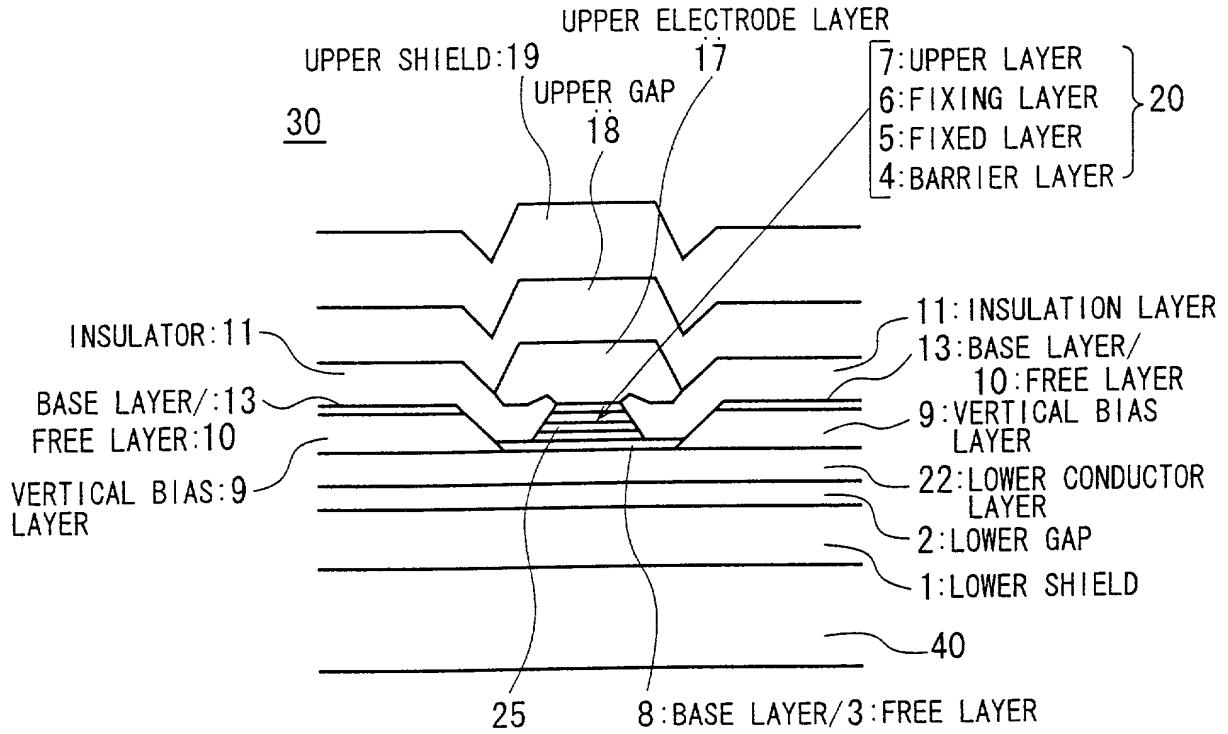


Fig.2

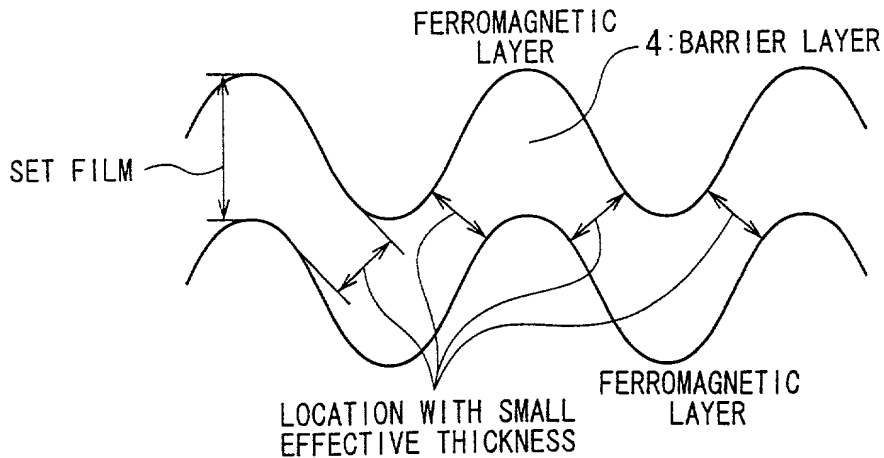


Fig.3

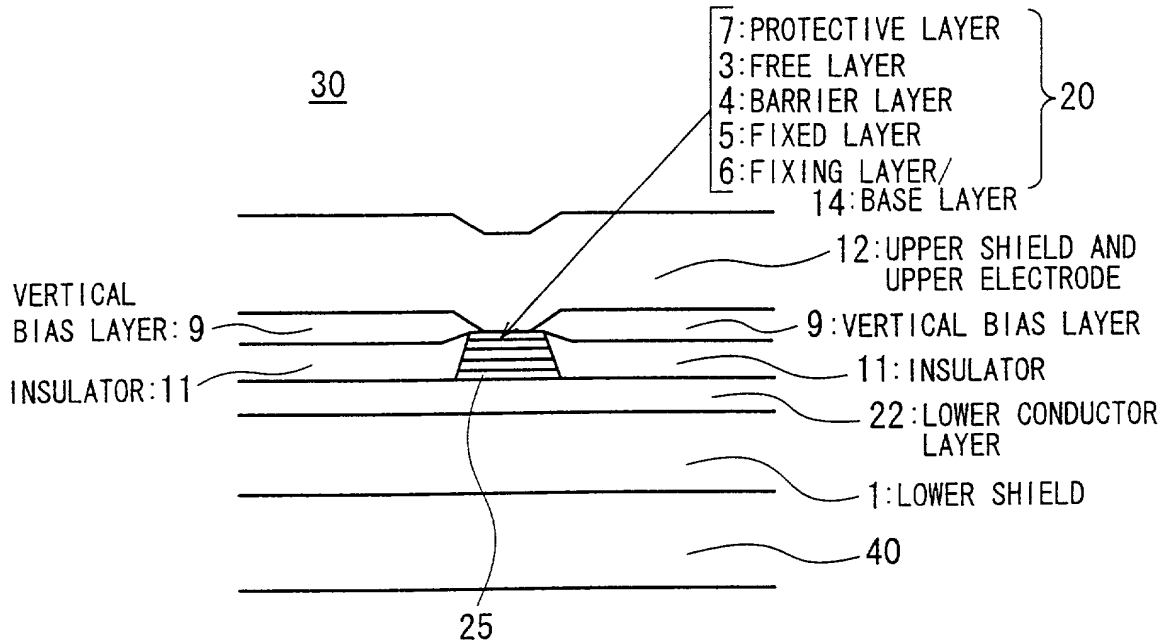


Fig.4

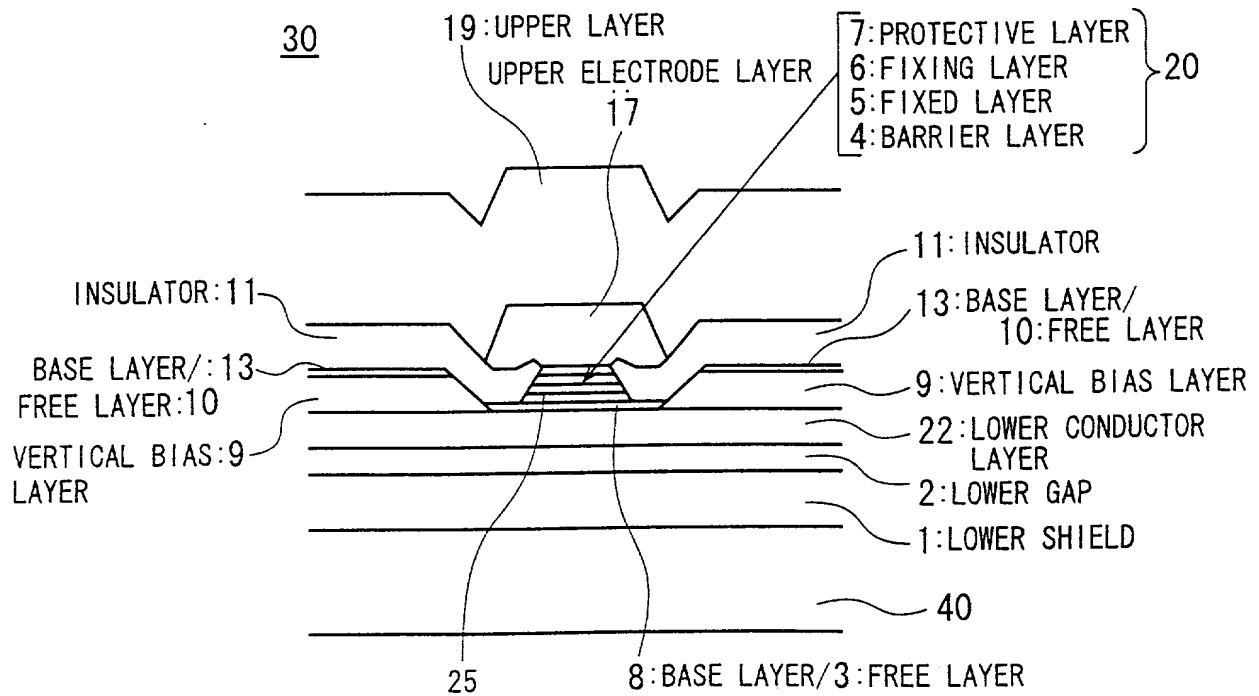


Fig.5

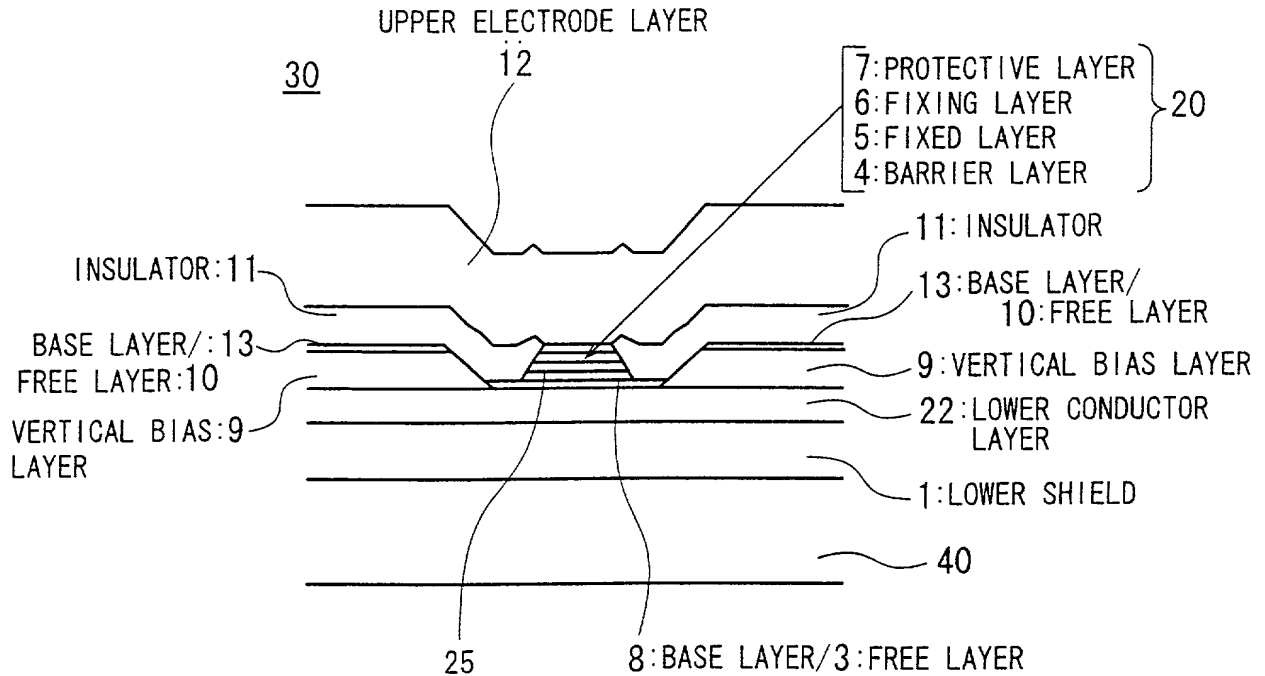


Fig.6

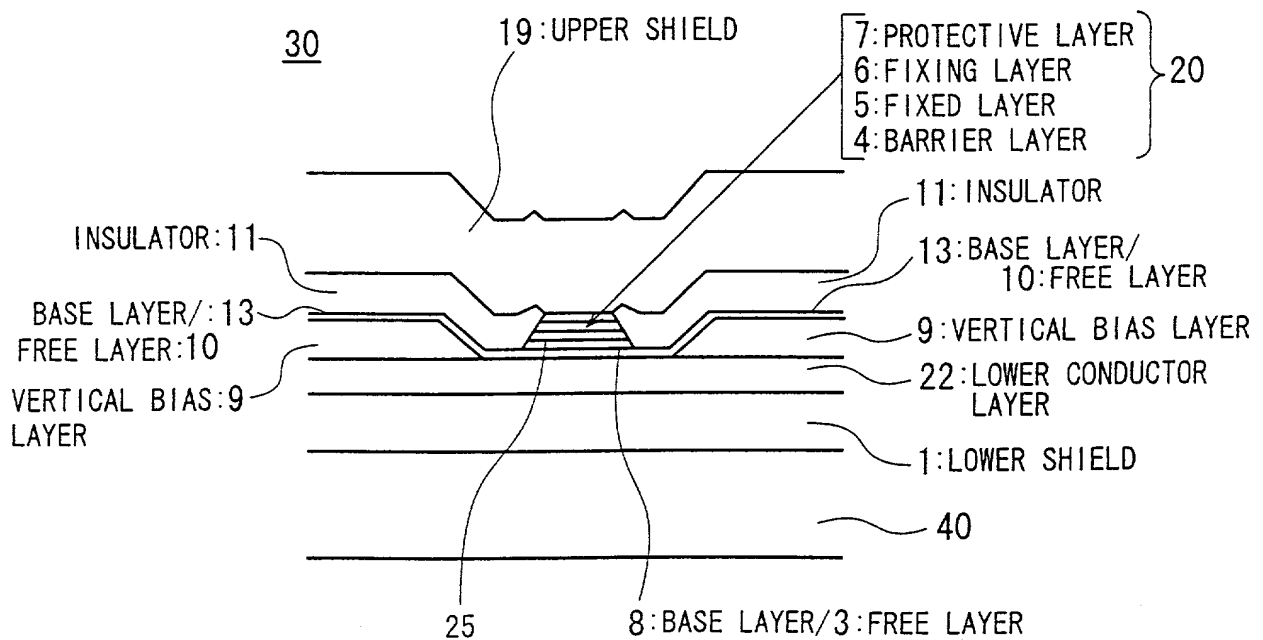


Fig.7

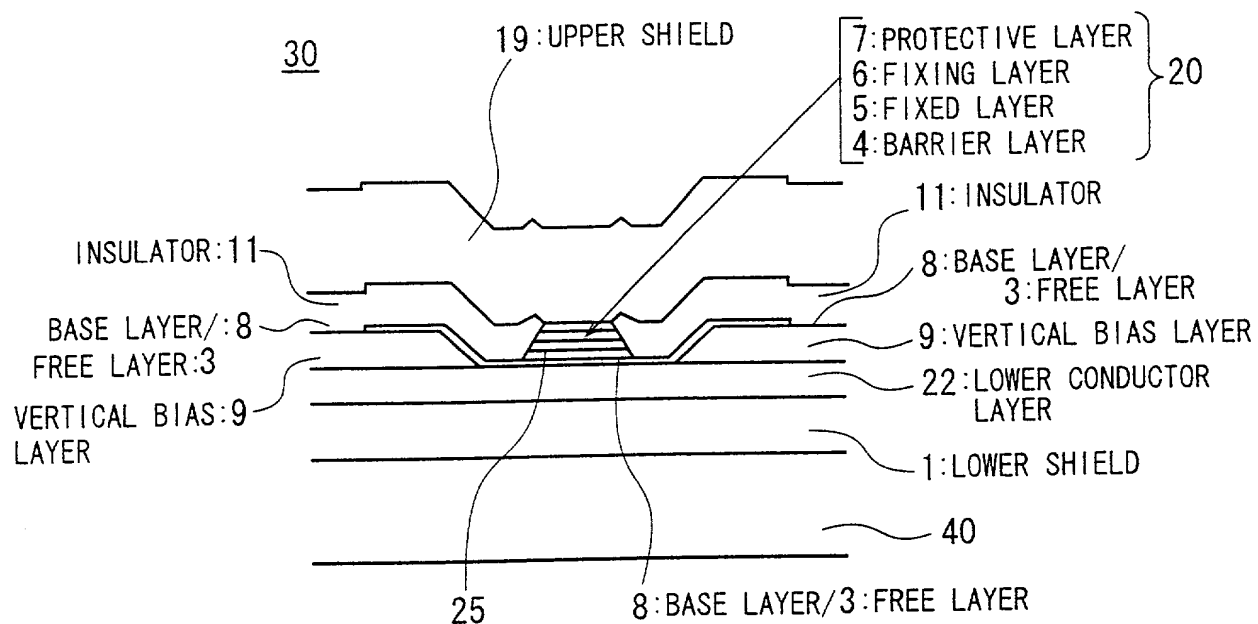


Fig.8

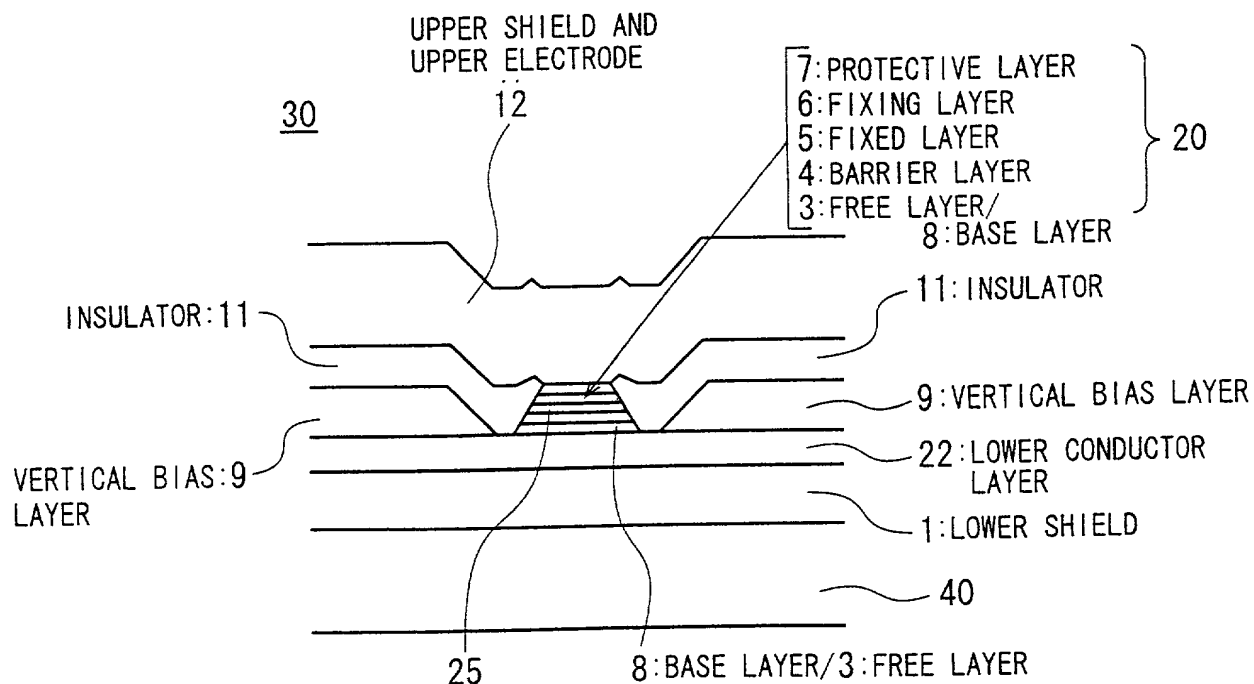


Fig.9

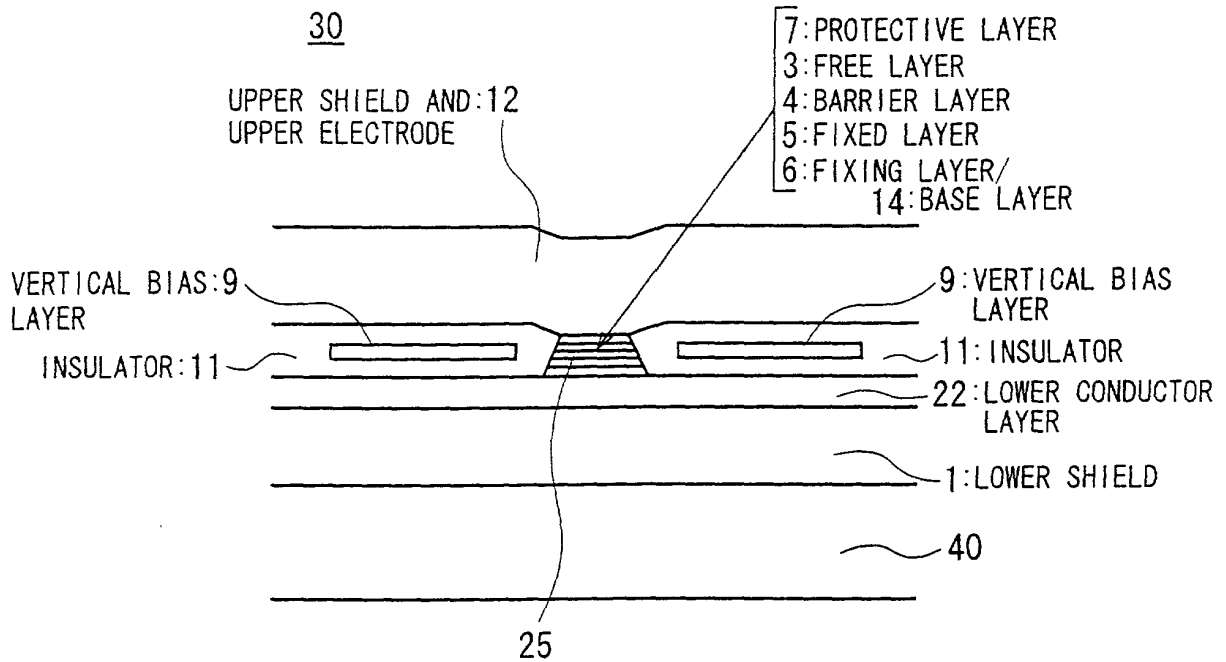
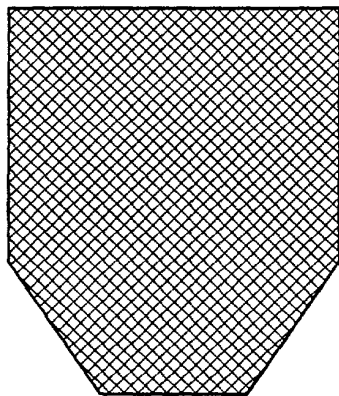
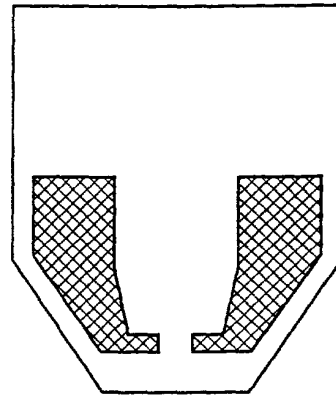


Fig.10(A)



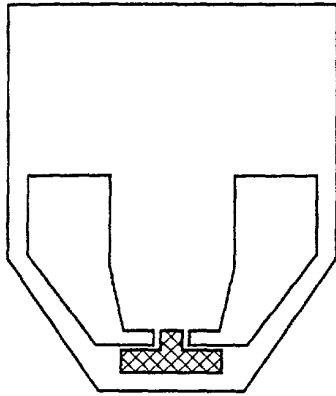
LOWER SHIELD AND LOWER CONDUCTOR
LAYER FORMED AS FILMS AND PATTERNED
(PR FORMATION → PR REMOVAL)

Fig.10(B)



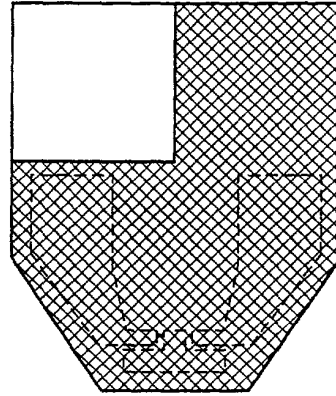
VERTICAL BIAS LAYER BASE LAYER/VERTICAL
BIAS LAYER FILM FORMATION AND PATTERNING
(PR FORMATION → PR REMOVAL)

Fig.11(A)



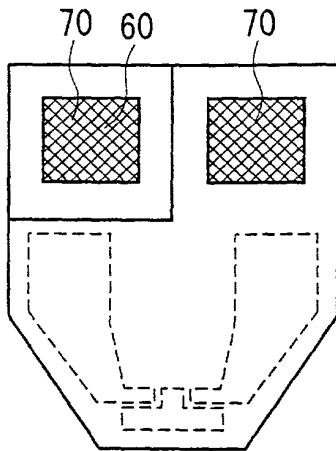
MAGNETORESISTIVE EFFECT FILM →
PR FORMATION → MILLING →
INSULATION FILM FORMATION → LIFT-OFF

Fig.11(B)



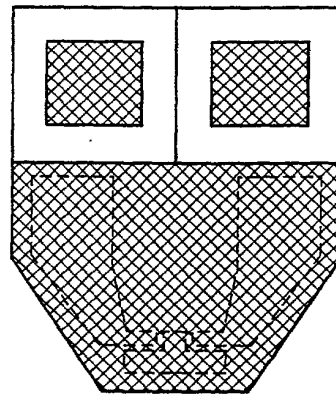
UPPER SHIELD FORMATION → PR FORMATION
→ PATTERNING → PR REMOVAL

Fig.12(A)



LOWER ELECTRODE HOLE FORMATION,
ELECTRODE TERMINAL FORMATION

Fig.12(B)



RECORDING HEAD FORMATION

Fig.13

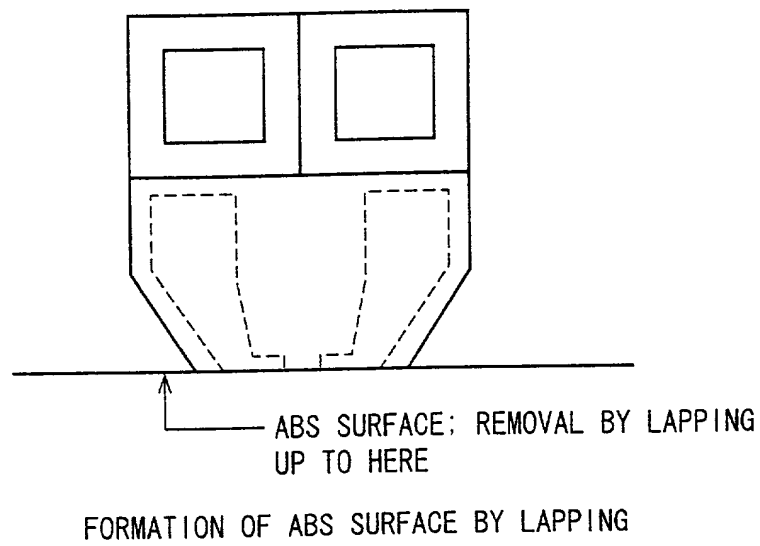


Fig.14

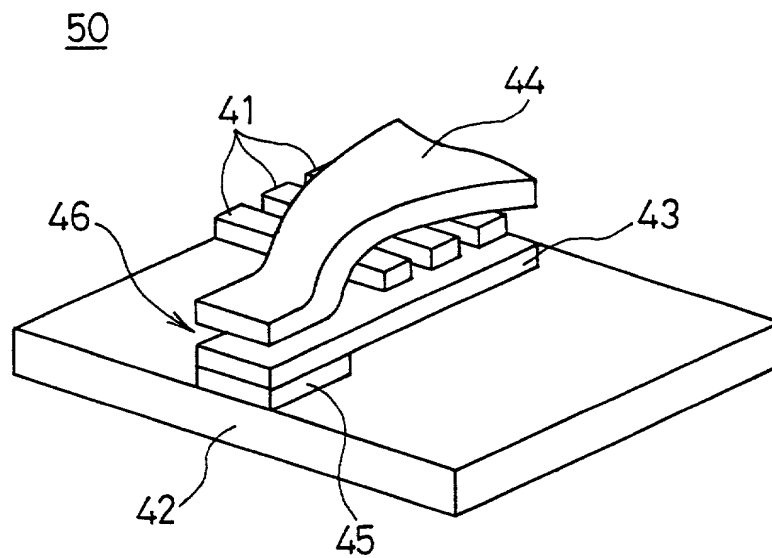


Fig.15

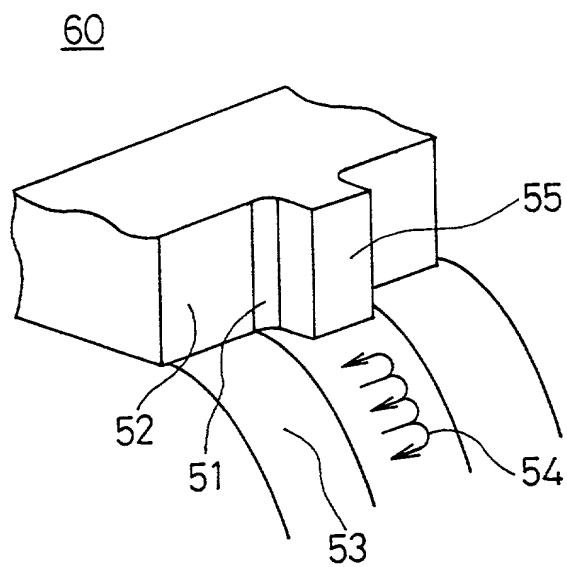


Fig.16

